IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A printed circuit board comprising:

~~constituted by alternately laminating interlayer resin insulating layers and conductive circuits on a core substrate containing a capacitor, an IC chip being mounted on an outer layer thereof, characterized in that~~

~~the core substrate containing said capacitor is constituted by providing a first resin substrate, a second resin substrate having an opening for containing the capacitor and a third resin substrate in a multilayer manner while interposing bonding plates, and the capacitor is located immediately below the IC chip,~~

a core substrate comprising a first resin substrate, a second resin substrate having an opening and a third resin substrate in a multilayer manner while interposing bonding plates;

insulating layers and conductive circuit layers alternately laminated on the core substrate;

a capacitor formed in the opening of the second resin substrate;

a first conductive pad [[is]] formed on the first resin substrate and connected to an electrode of the capacitor~~, and~~;

a second conductive pad formed on the first resin substrate and connected to the other electrode of the capacitor;

~~a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate.~~

a first via hole formed in the first resin substrate, the first via hole directly connected to the first conductive pad and a conductive circuit on the core substrate; and

a second via hole formed in the first resin substrate, the second via hole directly connected to the second conductive pad and a conductive circuit on the core substrate.

Claim 2 (Original): A printed circuit board according to claim 1, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 3 (Currently Amended): A printed circuit board according to claim 1, wherein each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 4 (Currently Amended): A printed circuit board according to claim 1, wherein ~~a plurality of capacitors are provided~~ the second resin substrate has a plurality of openings and a plurality of capacitors are formed in the openings.

Claim 5 (Original): A printed circuit board according to claim 1, wherein the conductor circuits are formed on said second resin substrate.

Claims 6-8 (Canceled).

Claim 9 (Currently Amended): A printed circuit board according to claim 1, further comprising:

a metal film formed on [[an]] the electrode of said capacitor.

Claim 10 (Original): A printed circuit board according to claim 9, wherein the metal film formed on the electrode of said capacitor is a plated film mainly consisting of copper.

Claims 11-14 (Canceled).

Claim 15 (Currently Amended): A printed circuit board constituted by alternately laminating ~~interlayer resin~~ insulating layers and conductive circuits on a core substrate containing a ceramic capacitor, ~~characterized in that~~ wherein

the core substrate containing said capacitor comprises ~~is constituted by providing~~ a first resin substrate, a second resin substrate having an opening for containing the ceramic capacitor and a third resin substrate in a multilayer manner while interposing bonding plates, ~~wherein~~

said first resin substrate and said ceramic capacitor are coupled to each other by an insulating bonding agent and a coefficient of thermal expansion of the insulating bonding agent is lower ~~in a coefficient of thermal expansion~~ than that of said first resin substrate,

a conductive pad is formed on the first resin substrate and connected to an electrode of the capacitor, and

a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate.

Claims 16-74 (Canceled).

Claim 75 (Currently Amended): A printed circuit board comprising:

a core substrate comprising a first resin substrate, a second resin substrate having an opening and a third resin substrate in a multilayer manner while interposing bonding plates;

insulating layers and conductive circuit layers alternately laminated on the core substrate;

~~an IC chip mounted on an outer layer of the insulating layers and the conductive circuit layers; and~~

a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area; and

a capacitor formed in the opening of the second resin substrate and located immediately below the bump area, ~~the IC chip;~~

wherein at least one of the bumps is electrically ~~IC chip is~~ connected to an electrode of the capacitor through a via hole formed in the core substrate, the via hole formed immediately below the bump area ~~IC chip~~.

Claims 76-78 (Canceled).

Claim 79 (Previously Presented): A printed circuit board according to claim 75, further comprising:

a metal film formed on the electrode of the capacitor.

Claim 80 (Previously Presented): A printed circuit board according to claim 79, wherein the metal film formed on the electrode of the capacitor is a plated film mainly consisting of copper.

Claim 81 (New): A printed circuit board according to claim 75, wherein the capacitor is a ceramic capacitor and each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 82 (New): A printed circuit board according to claim 75, wherein the capacitor is a ceramic capacitor and each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 83 (New): A printed circuit board according to claim 75, wherein an IC chip is to be mounted on the bump area.

Claim 84 (New): A printed circuit board according to claim 1, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area, wherein at least one of the bumps is electrically connected to the electrode of the capacitor through a via hole formed immediately below the bump area.

Claim 85 (New): A printed circuit board according to claim 84, wherein an IC chip is to be mounted on the bump area.

Claim 86 (New): A printed circuit board comprising:

a core substrate comprising a first resin substrate, a second resin substrate having an opening and a third resin substrate in a multilayer manner while interposing bonding plates;

insulating layers and conductive circuit layers alternately laminated on the core substrate; and

a ceramic capacitor formed in the opening of the second resin substrate,

wherein each of said first, second and third resin substrates has a core made of glass cloth and impregnated with a resin.

Claim 87 (New): A printed circuit board according to claim 86, further comprising:

a conductive pad formed on the first resin substrate and connected to an electrode of the capacitor; and

a via hole formed in the first resin substrate, the via hole directly connected to the conductive pad and the conductive circuit on the core substrate.

Claim 88 (New): A printed circuit board according to claim 86, wherein the capacitor is a ceramic capacitor and each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 89 (New): A printed circuit board according to claim 86, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area, wherein at least one of the bumps is electrically connected to the electrode of the capacitor through a via hole formed immediately below the bump area.

Claim 90 (New): A printed circuit board according to claim 89, wherein an IC chip is to be mounted on the bump area.